TSMC 06/07: LVDS



Libraries

Name	Process	Form Factor
RGO_TSMC06_18V25_6FF_UF_LVDS	6FF	Staggered Flip Chip
RGO_TSMC07_18V25_7FF_UC_LVDS	7FF	Staggered Flip Chip

Summary

The LVDS library provides an LVDS driver, receiver, and temperature stable voltage reference capable of supporting 16 drivers operating at data rates up to $4.0~{\rm Gbps}$.

LVDS Specification Compliant:

- TIA/EIA-644-A Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits
- IEEE Std 1596.3-1996

Additionally, this library provides a full complement of cells to support the assembly of a functional pad ring by abutment.

This library is offered at both 6nm and 7nm. It is available in a staggered flip chip implementation.

The included rail splitter allows multiple power domains to be isolated in the same pad ring while maintaining continuous VDD/VSS for robust ESD protection.

ESD Protection:

- JEDEC compliant
 - o 2kV ESD Human Body Model (HBM)
 - o 500 V ESD Charge Device Model (CDM)

Latch-up Immunity:

- JEDEC compliant
 - o Tested to I-Test criteria of ± 100mA @ 125°C

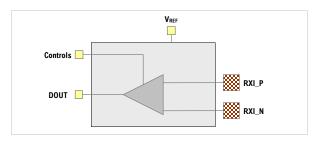
Cell Size & Form Factor

- Staggered (pad-limited) 46.38μm x 191.28μm
- Flip chip implementation with CUP structure built in

Recommended Operating Conditions

	Description	Min	Nom	Max	Units
V_{VDD}	Core supply voltage	0.675	0.75	0.825	V
V_{DVDD}	I/O supply voltage	1.62	1.8	1.98	V
TJ	Junction temperature	-40	25	125	°C
V_{PAD}	Voltage at PAD	-0.3V		V _{DVDD} +0.3V	V

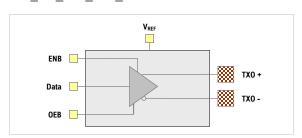
LDP_IN_800_25V_DN: 2.0 GHz LVDS Receiver



LVDS Receiver Features:

- Operates up to 2.0 GHz (4.0 Gbps)
- Input receive sensitivity of 75mV peak differential (without hysteresis)
- Common mode range from 0V to 2.4V (limited by power supply)
- Low power consumption

LDP_OU_800_18V_T: 2.0 GHz LVDS Driver



LVDS Driver Features:

- Operates up to 2.0 GHz (4.0 Gbps) with external 1pF load
- \bullet Common mode output range 1.1V $\pm 100 mV$
- Supports 100Ω differential terminations single ended
- Low power consumption

Characterization Corners

Model [1]	LPE Type	VDD= 0.75V	DVDD=1.8V	Temp
FF	Cbest_CCbest	+10%	+10%	-40°C
FF	Cbest_CCbest	+10%	+10%	o°C
FF	Cbest_CCbest	+10%	+10%	125°C
FFG	Ctypical	+10%	+10%	125°C
TT	Ctypical	nominal	nominal	25°C
TT	Ctypical	nominal	nominal	85°C
SS	Cworst_CCworst	-10%	-10%	-40°C
SS	Cworst_CCworst	-10%	-10%	0°C
SS	Cworst_CCworst	-10%	-10%	125°C

[1] Listed models are for 7FF. 6FF models are FFGNP / TT / SSGNP.

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Cell Summary

Name	Description
LDP_IN_800_25V_DN	LVDS receiver cell
LDP_OU_800_18V_T	LVDS driver cell
LDP_RE_000_18V	LVDS Voltage Reference cell
PVP_VD_RCD_10V	Core power (VDD)
PVP_VS_RCD_10V	Core ground (VSS)
PVP_VD_PDO_18V	I/O power (DVDD) with POC
PVP_VD_RDO_18V	I/O power (DVDD)
PVP_VS_RDO_18V	I/O ground (VSS)
SVP_SP_000_18V	0.1 µm spacer
SVP_SP_001_18V	1 µm spacer
SVP_SP_005_18V	5 μm spacer
SVP_SP_010_18V	10 µm spacer
SPP_RS_005_18V	Rail splitter

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